

**IN THE SPECIFICATION**

Please amend the specification as follows.

Please amend the paragraph beginning at page 14, line 12 as follows:

The larger array of the solder bumps 816 is processed differently to achieve a stress-relief layer. During processing a dispenser (not pictured) ejects a discrete series of quanta of compositions upon the land side 818, which is analogous to a lower surface where the die (not pictured) is on top of a package such as the die 110 in FIG. 1C is disposed on top of the package 102. The discrete series of quanta of compositions is also referred to by the reference numeral 826 as an SRL polymer mass 826 in an embodiment. FIG. 8 depicts flow characteristics of the discrete series of quanta of compositions 826 ~~824~~ as it encounters a solder first bump 816.